



Liu et al.
Serial No. 09/208,963
Filed December 10, 1998

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of)
John Liu et al.) Examiner Harry D. Wilkins III
Serial No. 09/208,963) Group Art Unit 1742
Confirmation No. 8859) Attorney Docket 97-2739
Filed December 10, 1998)
For High Toughness Plate Alloy For)
Aerospace Applications)

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AMENDMENT

I hereby certify that this correspondence is being deposited
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Julie W. Meder
Julie W. Meder - Reg. No. 36,216

Date of Signature: August 14, 2001

Assistant Commissioner for Patents

Washington, D.C. 20231

AMENDMENT

Sir:

In response to the Office Action dated May 10, 2001, Applicants submit the following amendments and remarks.

IN THE SPECIFICATION:

Please delete the paragraph bridging pages 3 and 4 and the first full paragraph on page 4, and replace them with the following replacement paragraphs. Pursuant to 37 CFR § 1.121 the following are clean copies of the replacement paragraphs. Marked-up versions are attached on separate sheets.